



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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**THERMOFIT[®] ADHESIVE AND SEALANT
THERMOFIT S-1124**

Thermofit S-1124 is a flexible adhesive based on elastomeric polymers. This adhesive was developed for use with Thermofit heat-shrinkable products, NT, NT-FR, and Elastomeric Polymer Blend (EPB). This adhesive provides good bonds of the heat-shrinkable materials to metals, such as steel and aluminum when bond line is heat to 150 °C (302 °F). The adhesive is supplied as a tape in .75 inch by .018 inch by 100 foot rolls, unless otherwise specified.

PROPERTY	UNIT	REQUIREMENT	METHOD OF TEST
PHYSICAL			
Visual Color		Pass Grey	Section 4.3.1.1
Specific Gravity		1.15 ± .05	Section 4.3.1.2 ASTM D 792
Adhesive Peel* EPB to EPB NT to NT EPB to NT EPB to Aluminum NT to Aluminum	Pounds/inch width	20 minimum 20 minimum 20 minimum 15 minimum 15 minimum	Section 4.3.1.9
CHEMICAL			
Water Absorption	Percent	0.5 maximum	Section 4.3.1.1 ASTM D 570
Corrosive Effect 16 hours at 121 °C (250 °F)		Pass	SECTION 4.3.2.2 ASTM D 2671 Method B
Fungus Resistance		Rating of 1 or less	Section 4.3.2.5 ASTM G 21
Solvent and Fluid Resistance** Weight change after 24 hours at 23 °C (74 °F): Hydraulic Fluid (MIL-H-46170) Aviation Gas (MIL-G-5572) Cleaning Compound (P-C-437) Isopropyl Alcohol (TT-I-735)	Percent	25.0 maximum 30.0 maximum 5.0 maximum 25.0 maximum	Section 4.3.2.6 ASTM D 543

Acceptance Tests: Visual and peel (EPB to EPB).

- * Prepare test specimens per Appendix F (including a solvent wipe) except heat for 30 minutes $150\text{ }^{\circ}\text{C}$ ($302\text{ }^{\circ}\text{F}$). NT or NT-FR may be used where NT is specified.

NT per RT-510
NT-FR per RT-511
EPB per RT-1321

- ** After immersion, specimens shall be lightly wiped and air dried 30 to 60 minutes at $23 + 2\text{ }^{\circ}\text{C}$ ($73 + 4\text{ }^{\circ}\text{F}$).